



## 微感測器 機械感測器

### Microsensors – Mechanical Microsensors

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## Sensors 的分類

- Smart Sensors: integrating sensor and signal processing units

表 6.1 感測器分類。根據 [Gard 94]。

信號形式	被 測 元
熱	溫度、熱量、熱流、焓、熱容等等。
輻射	伽瑪射線、X光、紫外光、可見及紅外光、微波、無線電波等等。
機械	位移、速度、加速度、力量、壓力、質量流、音波長度及振幅等等。
磁的	磁場、通量、磁矩、磁性、磁透率等等。
化學的	溼度、pH 值及離子、氣體濃度、毒性及有焰材料、蒸氣濃度及氣味、污染物等等。
生物的	糖、蛋白質、荷爾蒙（激素）、抗原等等。



## Major Applications - 1

- Medical Applications
  - ▶ 連續量測血液中的物理化學參數如溫度、壓力、流量、pH值
  - ▶ 呼吸系統中的氧、二氧化碳或麻醉劑
  - ▶ 體內量測 (*In situ* measurement)
    - 感測器需與生物相容，且長時間穩定，不需外加電源
- Environmental Protection
  - ▶ 偵測物質（氣體、液體的固形量）濃度，如一氧化碳、氧化氮、重金屬
  - ▶ 大氣中的二氧化碳濃度
  - ▶ 需常暴露於污水與垃圾中，感測器晶片可於現場同時進行資料的處理，減少訊號傳輸的必要性
- Food Processing: 化學與生物感測器以偵測污染與不純物



## Major Applications - 2

- Automobile Applications
  - ▶ Distance, acceleration, pressure, vibration, temperature and chemical sensors
  - ▶ 增加安全性與降低燃油消耗與污染
- Microrobotics
  - ▶ Often equipped with distance, acceleration, force, torque, tactile, pressure and temperature sensors.
- Materials: semiconductor materials, metals, plastics, ceramics, glasses, enzymes and antibodies (biosensors)
- Fabrication: Silicon technology, LIGA



## Pressure Sensors

- First developed and used by industry
- Silicon-based pressure sensor: low cost, high sensitivity, and low hysteresis
- Typical pressure sensor
  - ▶ Deflection Membrane structure is proportional to pressure
  - ▶ Piezoresistive pressure sensor
  - ▶ Capacitive pressure sensor
  - ▶ Resonance pressure sensor
  - ▶ Interferometer pressure sensor



## Piezoresistive Pressure Sensor

- Bulk micromachining of a (100) silicon substrate
  - ▶ Etch stop to produce membrane
  - ▶ Piezoresistors integrated in the membrane
  - ▶ Wheatstone bridge measure the change of resistance

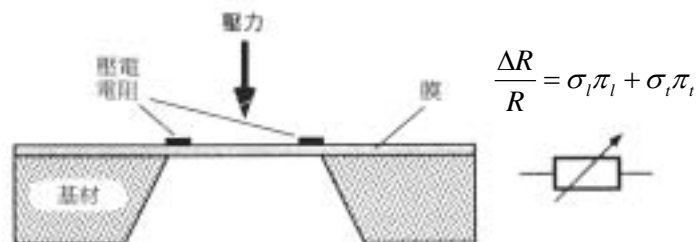


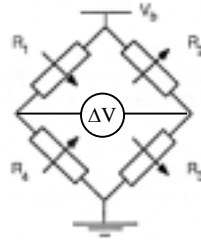
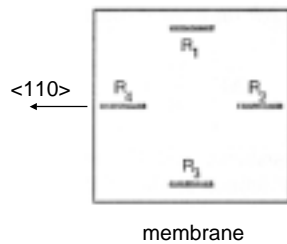
圖 6.4 壓電阻抗壓力感測器原理。根據 [Heub 91]。





### Wheatstone Bridge Connection

- p-type resistors are preferable since their piezoresistive coefficient is a maximum in (110) direction, whereas the n-type coefficient have a minimum in that direction.
- Schematic representation of the basic position of four piezoresistors on a membrane.

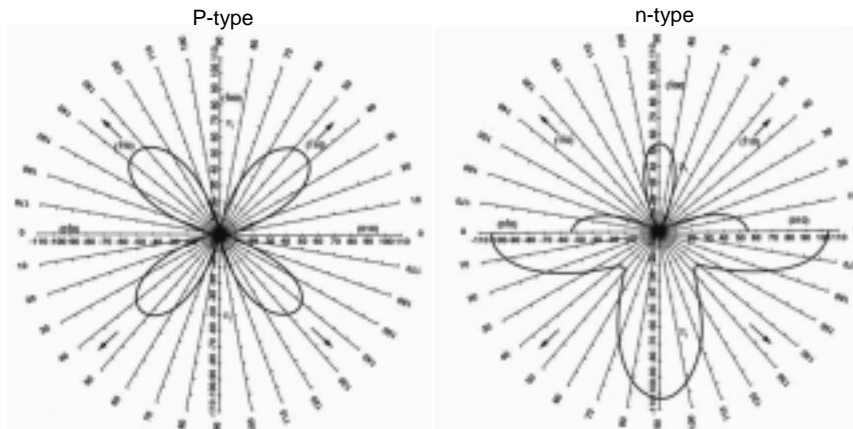


$$\Delta V = \frac{\Delta R}{R} V_b$$



### Piezoresistance Coefficients

- Piezoresistance Coefficients  $\pi_l$  and  $\pi_t$  for (100) silicon.



Source: Fundamental of Microfabrication, p.202





## Schematic Illustration of Pressure Microsensor

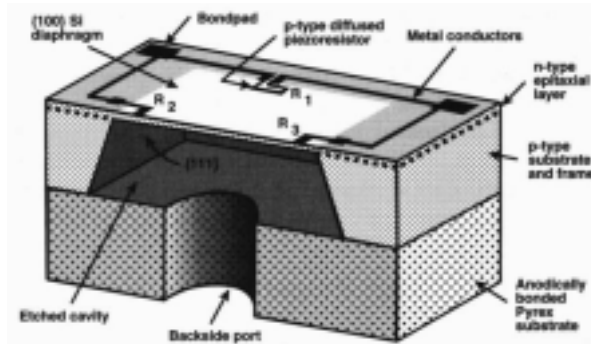


Figure 4.24 Schematic illustration of a pressure sensor with p-type diffused resistor in an n-type epitaxial layer. (Based on N. Maluf, *An Introduction to Microelectromechanical Systems Engineering*, Artech House, Boston, 2000.<sup>30</sup>)

Source: Fundamental of Microfabrication, p.203



## Membrane Stresses

### ■ Assumptions:

- ▶ Deflections are very small compared to the membrane thickness.
- ▶ No deformation in the middle plane.
- ▶ Normal stresses in the direction transverse to the plate can be neglected.

### ■ Surface stress in the middle of the sides of the membrane:

- ▶  $p$ : pressure
- ▶  $a$ : membrane side length
- ▶  $h$ : membrane thickness

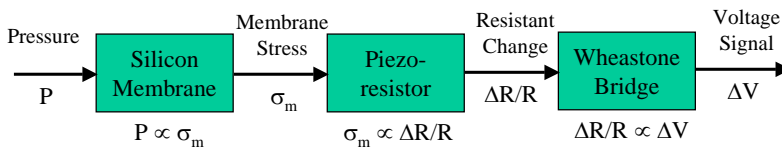
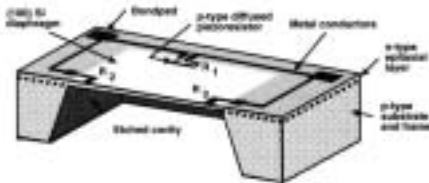
$$(\sigma_x)_{\max} = 0.31p \frac{a^2}{h^2}$$





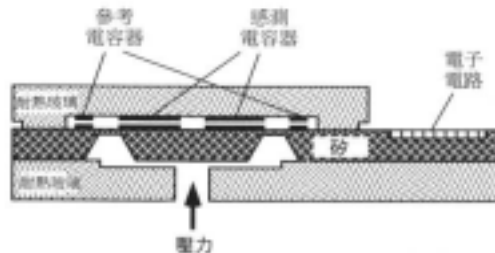
## 壓阻式微壓力計的感測轉換機制

- 藉由感測器結構與電路設計  
將壓力轉換成電壓訊號
  - ▶ 矽薄膜：將壓力轉換為薄膜應力
  - ▶ 壓阻材料(P+ doping silicon)：將薄膜應力轉換為電阻改變率
  - ▶ 惠斯敦電橋：將電阻改變率轉換為電壓偏移量



## Capacitive Pressure Sensor

- Displaced mass changes the capacitance between two attached metal plates.
- KOH anisotropic etching silicon substrate sandwiched between two Pyrex glasses through anodic bonding.



$$C = \epsilon \frac{A}{d}$$

$$\frac{\Delta C}{\Delta d} = -\epsilon \frac{A}{d^2}$$

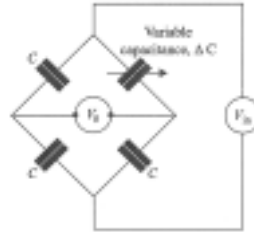
圖 6.5 由矽所製之電容性壓力感測器。根據 [Mehl 92]。



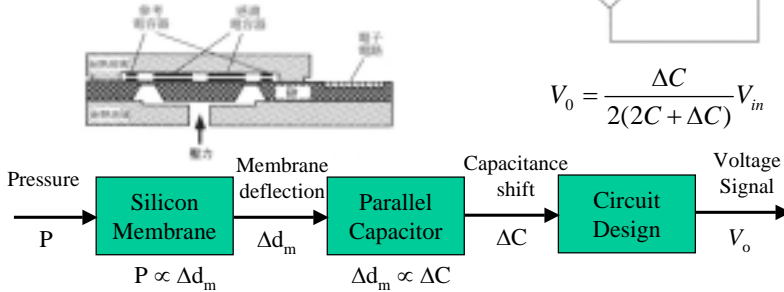
## 電容式微壓力計的感測轉換機制

■ 藉由感測器結構與電路設計將壓力轉換成電壓訊號

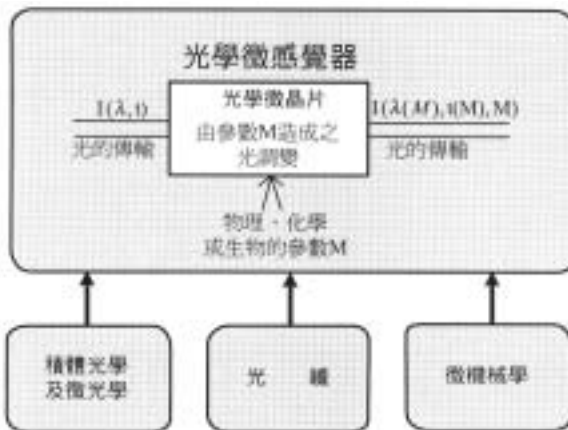
- ▶ 矽薄膜：將壓力轉換為薄膜位移量
- ▶ 平行電容結構：將薄膜位移量轉換為電容改變量



$$V_o = \frac{\Delta C}{2(2C + \Delta C)} V_{in}$$



## Microoptical Systems



■ Optical Parameters

- ▶ Amplitude
- ▶ Phase shift
- ▶ Spectral distribution
- ▶ Frequency
- ▶ Time

圖 6.1 光學微感測器之架構。根據 [Lore 93]。



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## 光晶片的波導

折射之步階指數

折射之漸變指數

$n_1, n_2, n_0$  - 蕊, 基材及表面之折射指數

圖 6.3 玻璃光纖之剖面

CFD 15

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## Reflection and Refraction

- Law of reflection
  - ▶  $\theta'_1 = \theta_1$
- Law of refraction
  - ▶  $n_1 \sin \theta_1 = n_2 \sin \theta_2$
- Refraction rate
  - ▶  $c$ : 光在空氣中的速度
  - ▶  $v_m$ : 光在介質中的速度
$$n_m = \frac{c}{v_m}$$

(b)

CFD 16





## Total Reflection

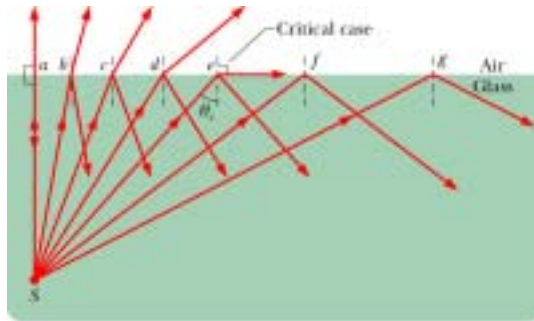
■ Total Internal reflection

- ▶  $n_1 \sin\theta_c = n_2 \sin 90^\circ$
- ▶ Critical angle

$$\theta_c = \sin^{-1} \frac{n_2}{n_1}$$

■ Typical materials

- ▶ SiO<sub>2</sub>/SiON/SiO<sub>2</sub>
- ▶  $n(\text{SiO}_2)=1.46$
- ▶  $n(\text{SiON})=1.52$



## Mach-Zehnder Interferometer

■ Waveguide deforms and changes the properties of the light beam

■ Use phase shift to measure pressure

■ Integrate SiON waveguides, sensitive silicon membranes, photodiodes, and CMOS amplifier.

■ Sensitivity 14  $\mu\text{V}/\text{mbar}$

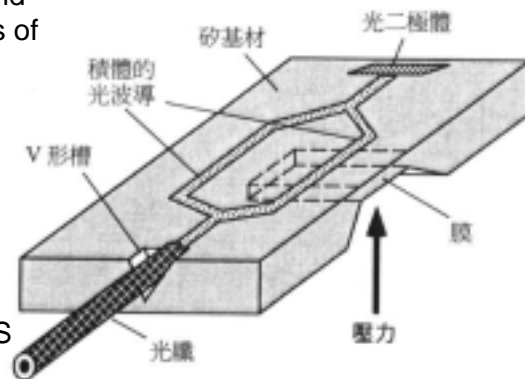
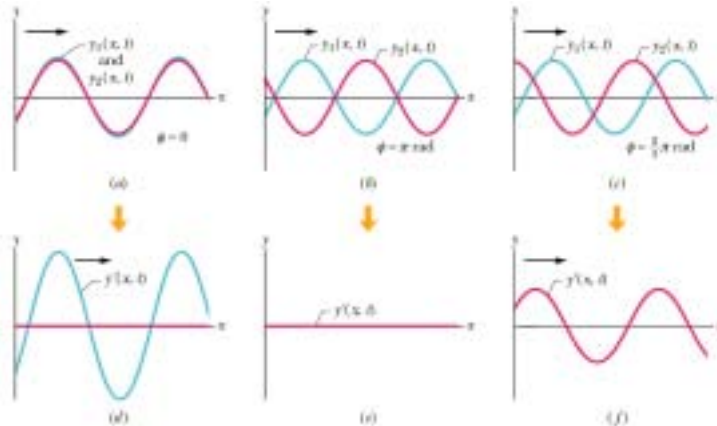


圖 6.8 馬赫切德干涉儀。根據 [Fisch 91]。



## Interference of Waves

- (a) Fully constructive interference, (b) Fully destructive interference, and (c) intermediate interference



## Interferometer

- Superposition of two identical waves with a phase shift.

$$\begin{aligned}
 \blacktriangleright y'(x, t) &= y_1(x, t) + y_2(x, t) \\
 &= y_m \sin(kx - \omega t) + y_m \sin(kx - \omega t + \phi)
 \end{aligned}$$

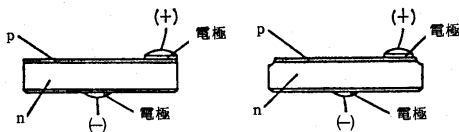
$$\underbrace{y'(x, t)}_{\text{Displacement}} = \underbrace{[2y_m \cos \frac{1}{2} \phi]}_{\text{Amplitude}} \underbrace{\sin(kx - \omega t + \frac{1}{2} \phi)}_{\text{Oscillating term}}$$





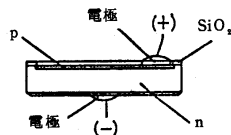
## Photodiodes

- pn接合的半導體內有光射入時，激發正子與電子對，正子往p層電子往n層移動，產生的電流  $I_{ph}$  與入射光的能量呈正比



(a) 標準型

(b) 凸型



(c) 平面型

圖 1 矽受光元件的構造

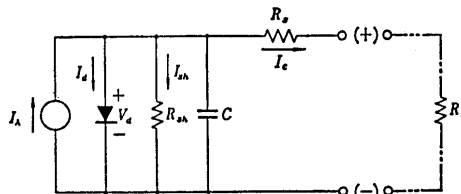


圖 2 矽受光元件的等效電路



## Wave Guide of Pressure Sensors

- Consist of the light guiding layer (SiON) and a lower index of refraction (SiO<sub>2</sub>) to allow the passage of light
  - A 2 to 3 μm thick silicon dioxide layer (index of refraction = 1.46) was applied to a (100) silicon wafer.
  - Deposit a 0.5 μm thick light guiding layer made of SiON (index of refraction = 1.52).
  - A 0.6 μm thick silicon dioxide layer was added and structured using a dry etching process.

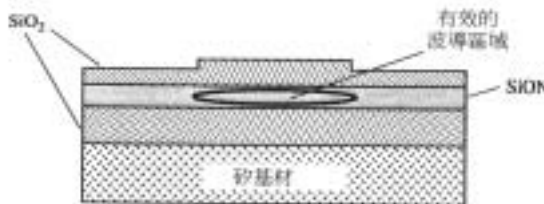
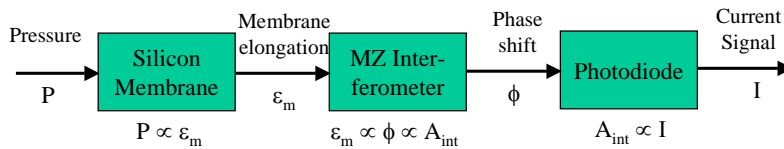
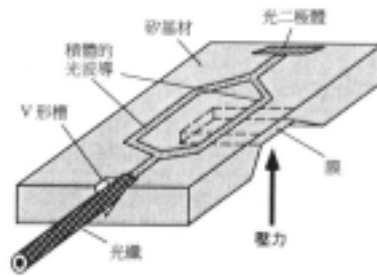


圖 6.9 壓力感測器之波導。根據 [Hill 94]。



## 光干涉儀式微壓力計的感測轉換機制

- 藉由感測器結構與光路設計  
將壓力轉換成電流訊號
  - ▶ 矽薄膜：將壓力轉換為薄膜變形量
  - ▶ 干涉儀：將薄膜變形轉換為光路的相位差，因而改變干涉的光強度
  - ▶ 光二極體：將光強度轉換為感應電流



## Comparisons of Pressure Sensors

- Compared to piezoresistive signal transformers, capacitive pressure sensors have no hysteresis, a better long-term stability and a higher sensitivity.
- Capacitive pressure sensors have higher production costs, and the circuit design is more difficult.
- Interferometer pressure sensors have a much higher sensitivity.





## Capacitive Force Sensor

- A movable elastic structure transforms a force into a displacement.
- A transformation unit consisting of the electrodes transforms the displacement into a measurable change of capacitance.
- Better linearity and less cross-sensitivity.
- Made by anisotropically etching (110) silicon

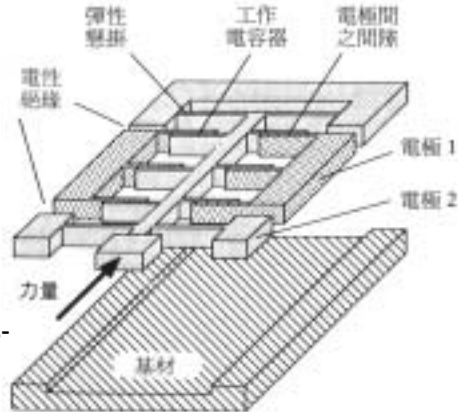


圖 6.6 矽製之電容式力感測器 - 根據 [Desp 93] =  
20 nm resolution, 0.01 ~ 10 N



## Force Sensing Resistor

- Resistance is inversely proportional to the pressure
- Polymer foil with planar electrodes covered by semiconductor polymer
- Applied force reduces the resistance due to current flows across the shunting polymer foil
- Dynamic range affected by electrode pitch and sensitivity affected by foil thickness
- Major disadvantage: hysteresis

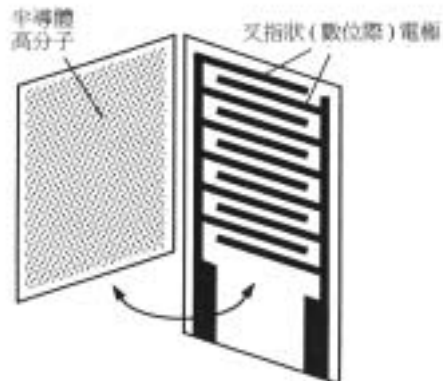
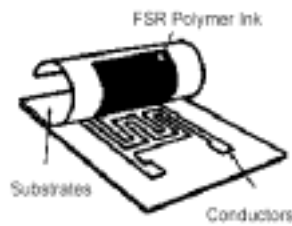


圖 6.10 力量偵測電阻 - 根據 [Witte 92] =  
5% deviation, 10g ~ 10Kg

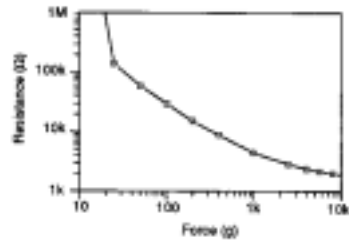


## *Force Sensing Resistor 功能及用途*

- 高分子膜加上平面電極，再加上一半導體高分子膜
- 當此裝置受一力時，電阻值會降低，即壓力與電阻成反比。
- 量測電阻值範圍1 MOhm(百萬歐姆)~2 KOhm，力量感測約10g~10kg



<http://www.steadlands.com>



## *Position and Speed Microsensors*

- Essential for automobiles, robots and medical instruments.
- Determine the exact position of an endeffector of a microrobotics.
- Contact-free optical and magnetic methods are the most significant ones:
  - ▶ Magnetic sensor for angular displacement
  - ▶ Inclination sensor
  - ▶ Ultrasound distance sensors
  - ▶ Capacitive rotational speed sensor
  - ▶ Fiber optical swing angle sensor



## Magnetic Sensor for Angular Displacement

- Use Hall effect to detect angular displacement

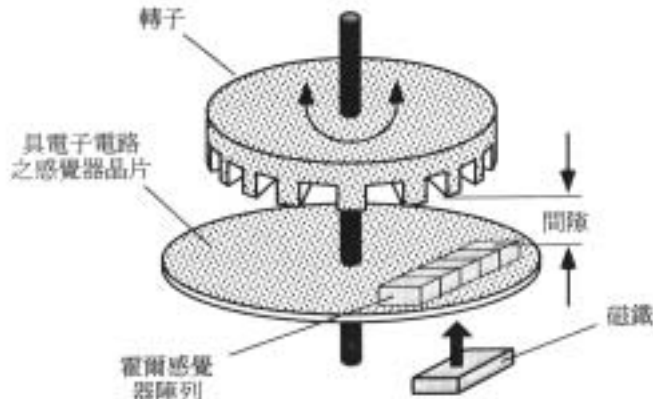


圖 6.12 角度量測微感測器。根據 [Ueno 91]。



## Hall Effect

- Magnetic Force (Lorenz Force)

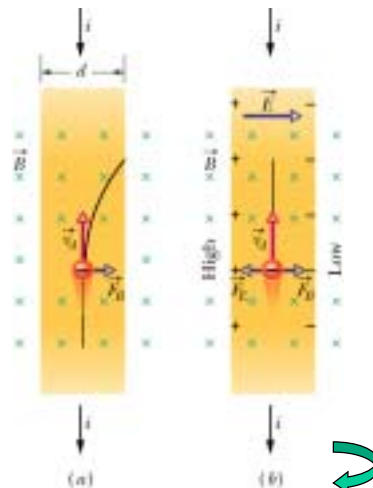
- ▶  $\vec{v}$  : the velocity of charge  $q$
- ▶  $\vec{B}$  : magnetic field

$$\vec{F}_B = q\vec{v} \times \vec{B}$$

- Hall Effect

- ▶ The separation of positive and negative charges produces an electric field  $E$
- ▶ The force due to  $\vec{E}$  and the force due to  $\vec{B}$  are in balance.
- ▶ Hall potential difference  $V$

$$V = Ed$$



### Block Diagram for Magnetic Sensor

- Each Hall sensor covers one tooth and one notch of the rotor
- Multiplexer scans all  $n$  Hall sensor creating a step function to represent the magnetic distribution
- Rotation causes phase shift
- Accuracy of  $0.028^\circ$

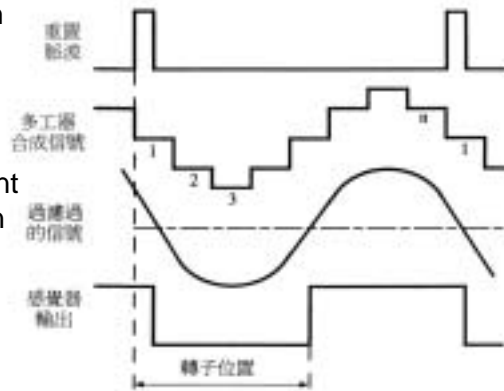


圖 6.13 量測程序之方塊圖。根據 [Ueno 91]。

### Inclination Sensor

- Consists of an LED and a semi-spherical glass cup mounted on a photodiode matrix array

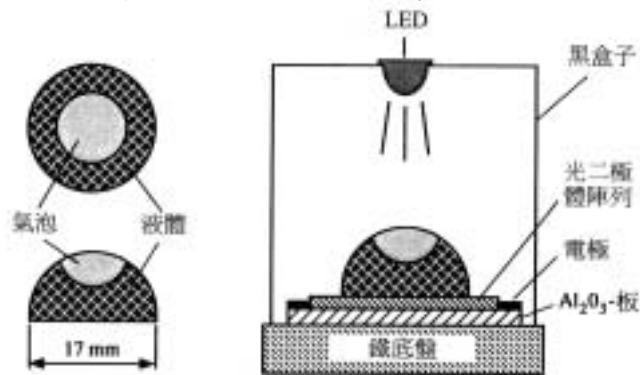


圖 6.14 傾斜感測器。根據 [Kato 91]。





## Principle of Inclination Sensor

- Speed should keep constant
- Accurate for small angle ( $10^\circ$ )

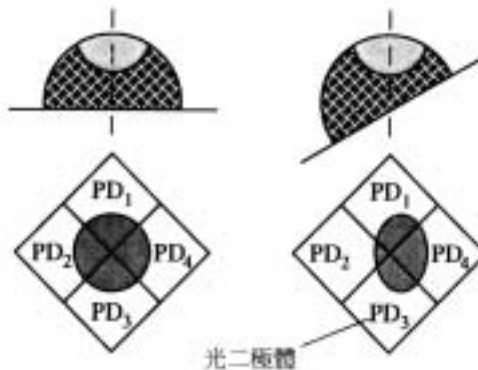


圖 6.15 感測器的量測原理。根據 [Kato 91]。

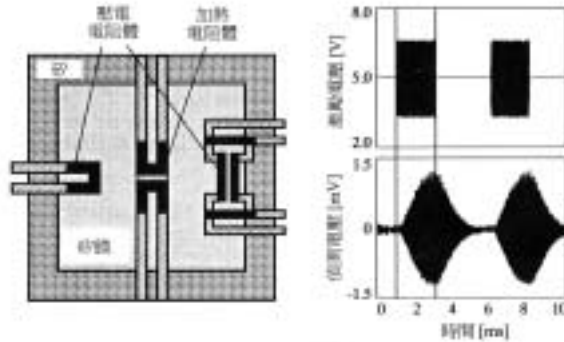


## Ultrasound Distance Sensors

- Use the pulse-echo principle.
- Ultrasound transducer made from piezoceramics emits a pulse sequence.
- "Blind spot" appears when the detector is too close to an object .
- Two identical independent ultrasound membranes, one transmitter and one receiver, integrated on a silicon substrate.
- Membrane is brought to resonance with integrated heating resistors.
- Acoustic pressure response is detected by piezoresistors, integrated in the form of a Wheatstone bridge.

### Ultrasound Distance Sensors

- Schematic design of a single sensor membrane and the measurement principle



Sensitivity  $3 \mu\text{V}/\text{mPa}$ , at a bridge voltage of 5V.

圖 6.16 超音波距離感測器。(a) 感測器之設計。(b) 感測器之量測原理。根據 [M'S'93]。

### Capacitive Rotational Speed Sensor

- Compact and inexpensive angular speed sensors in navigation and landing gear controllers

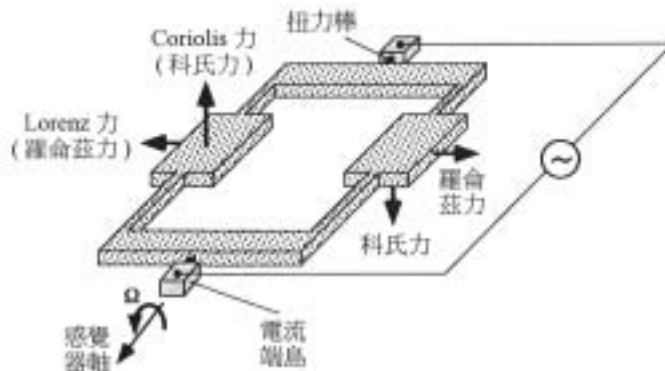


圖 6.17 旋轉速度微感測器之工作原理。根據 [Hash 94]。

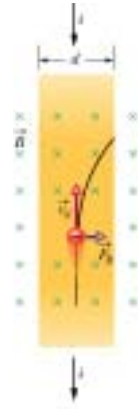
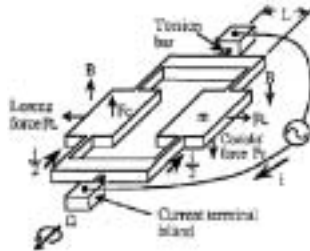
## Lorenz Force (羅倫茲力)

■ Lorenz Force (羅倫茲力)：運動中帶電粒子的磁力

- ▶ 當帶電粒子  $q$  以一速度  $v$  垂直進入磁場  $B$  中，它會承受一偏向力  $F_B$ ，稱為羅倫茲力。

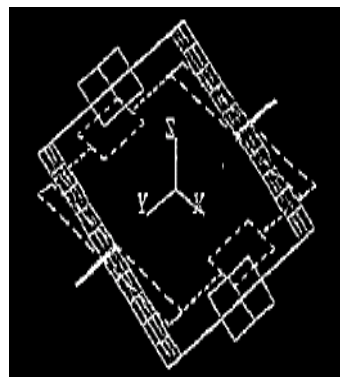
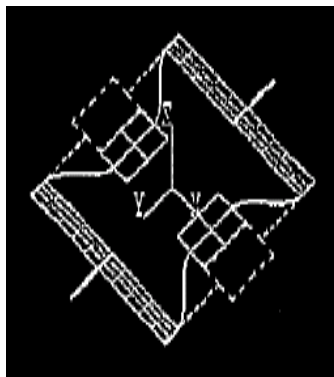
$$\vec{F}_B = q\vec{v} \times \vec{B}$$

- ▶ 當輸入電流為交流電，質塊因Lorenz Force而震盪



## Capacitive Rotational Speed Sensor

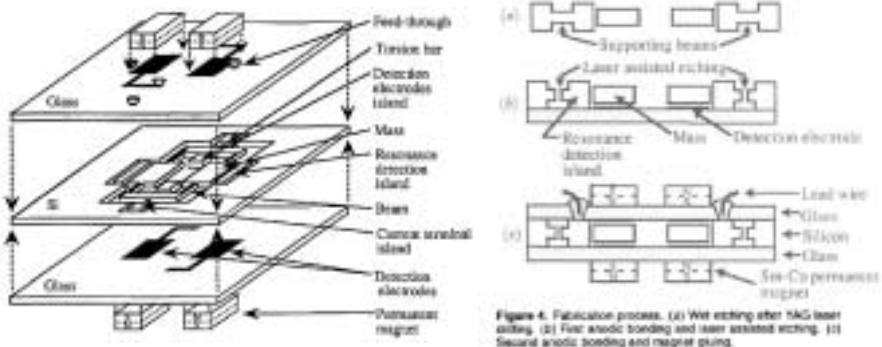
■ 感測器運動模擬





## 電容式角速度感測器結構

- Made of (110) silicon



[Hashimoto, in Micro System Technologies, 94]



## Fiber Optical Swing Angle Sensor

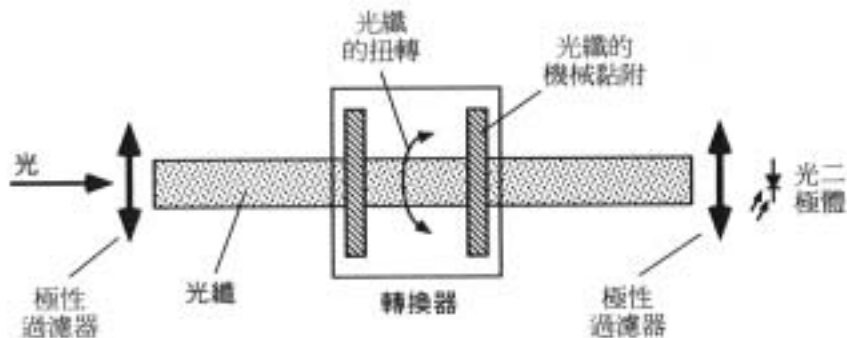
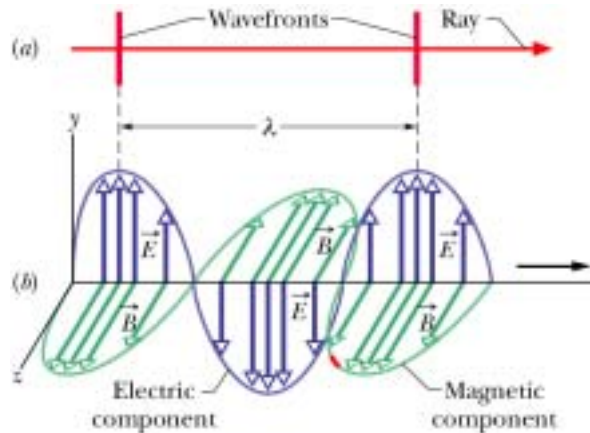


圖 6.18 光纖擺角度感測器。根據 [Ecke 93]。



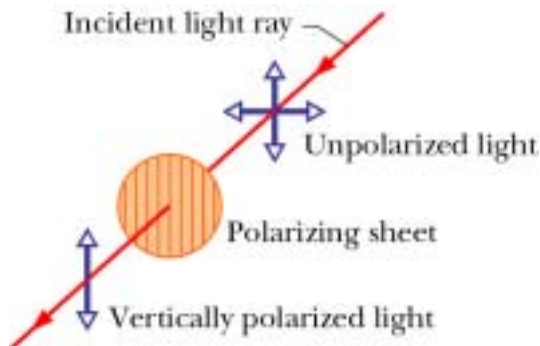
## Electromagnetic Wave

- An electromagnetic wave represented with a ray and two wavefronts.

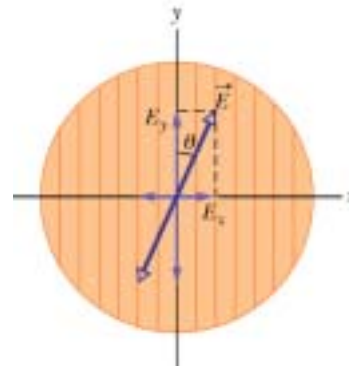


## Polarization Filter

- Unpolarized light becomes polarized when it is sent through a polarization filter.



$$E_y = E \cdot \cos\theta$$





## Fiber Optical Swing Angle Sensor

- Light is lead into a glass fiber via a polarization filter.
- A torque applied to the mechanical measuring section causes a torsion in the glass fiber and changes the direction of the polarization of the light.
- Change of the light intensity is detected by the second polarization filter and is then evaluated by a photodiode.



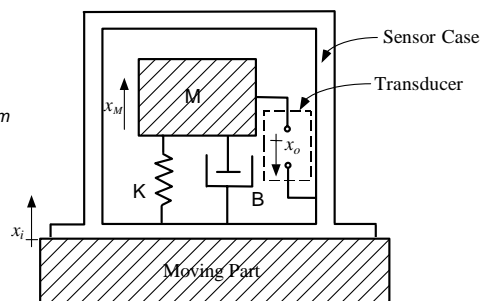
## Typical Model of Accelerometer

### ■ STRUCTURE OF ACCELEROMETER

- ▶ Mass-Spring-Damper substructure
- ▶ Displacement transducer
- ▶ Amplification circuit

### ■ SYSTEM MODEL

- ▶ Mechanical subsystem  $G_m$
- ▶ Electric subsystem  $G_e$





## Mechanical Subsystem

### MASS-SPRING-DAMPER SUBSTRUCTURE

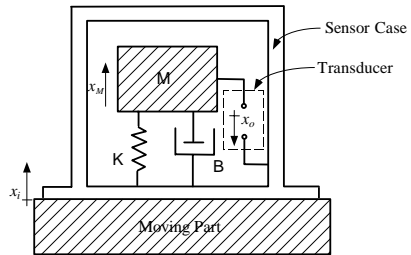
$$M\ddot{x}_i = M\ddot{x}_o + B\dot{x}_o + Kx_o$$

### NEWTON'S SECOND LAW

$$\frac{x_o}{\ddot{x}_i}(D) = S_m \cdot \frac{\omega_n^2}{D^2 + 2\zeta\omega_n D + \omega_n^2}$$

### MECHANICAL TRANSFER FUNCTION

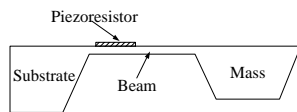
where  $\omega_n = \sqrt{\frac{K}{M}}$      $\zeta = \frac{B}{2\sqrt{KM}}$      $S_m \equiv \frac{M}{K}$



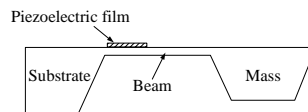
## Cantilever Principles

### DISPLACEMENT TRANSDUCER OF ACCELEROMETER

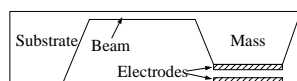
- ▶ Piezoresistive
- ▶ Capacitive
- ▶ Piezoelectric



(a) Piezoresistive Mode



(c) Piezoelectric Mode



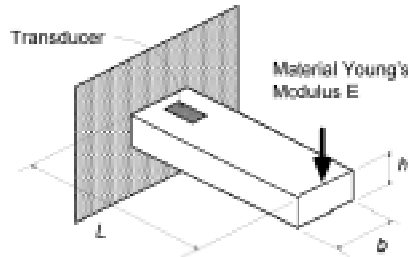
(b) Capacitive Mode



## Cantilever Beam Spring

### ■ 懸臂樑在自由端受負載之最大變形

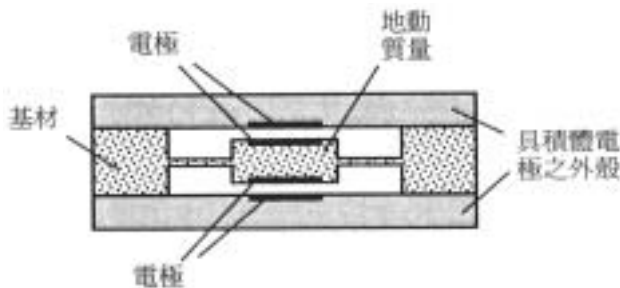
- ▶  $y_{max} = PL^3 / (3EI)$
- ▶ 虎克定律
  - $P = Ky$
  - $P = (3EI/L^3) \cdot y_{max}$
  - 懸臂樑的彈簧常數  $K = (3EI) / L^3 = (Ebh^3) / (4L^3)$



## Capacitive Microaccelerometer

### ■ 質塊位移造成電容的改變

- ▶  $\epsilon$ : Permittivity,  $A$ : area,  $d$ : distance,  $V$ : voltage,  $Q$ : charge
- ▶  $\epsilon_0$ : Permittivity in vacuum,  $\epsilon_r$ : Dielectric constant



$$C = \epsilon \frac{A}{d}$$

$$C = \frac{Q}{V} \quad \epsilon_r = \frac{\epsilon}{\epsilon_0}$$

$$\frac{\Delta C}{\Delta d} = -\epsilon \frac{A}{d^2}$$

圖 6.19 加速度的電容性量測



### Piezoresistive Micro-accelerometers

- 在應變最大處鍍上壓阻 (Piezoresistive) 材料
- 加速度造成質塊位移而在懸樑上產生應變

$$\frac{\Delta R}{R} = \sigma_l \pi_l + \sigma_t \pi_t$$

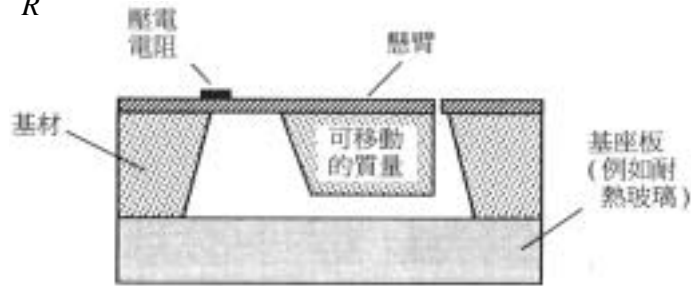
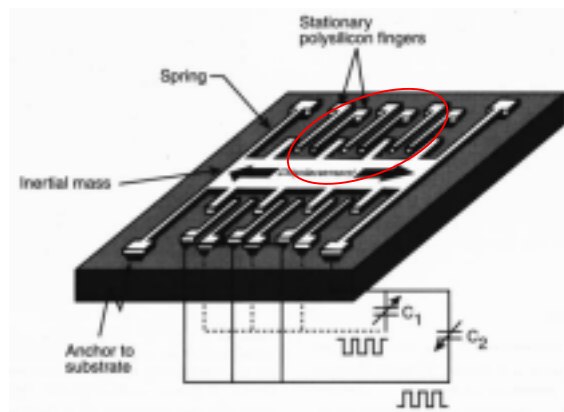


圖 6.20 壓電電阻加速度感測器。

### Integrated Capacitive Accelerometer

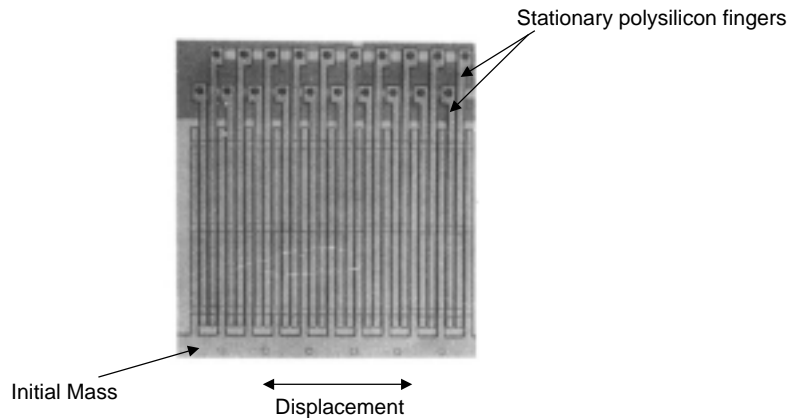
- Consists of independently fixed plates and a movable comb-like microstructure.





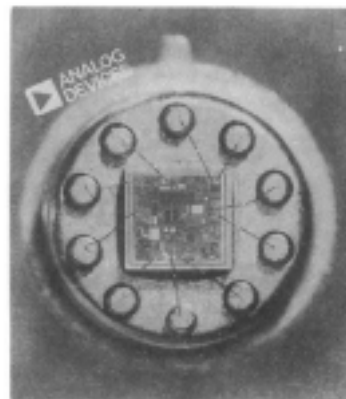
## *Integrated Capacitive Accelerometer*

- Made from polysilicon by surface micromachining.



## *Integrated Capacitive Accelerometer*

- First commercialized MST device. Used in airbag system.
- Sensor diameter about 9 mm.
- Signal pre-amplification, temperature compensation and system self-test purposes were integrated
- Accelerations up to  $\pm 50$  g can be measured with a sensitivity of 10 mV/g.





## Capacitive Cantilever Microsensor

- Consist of a cantilever beam over an opposite electrode and a contact strip.
- Threshold voltage applied to offset the forces caused by the acceleration.

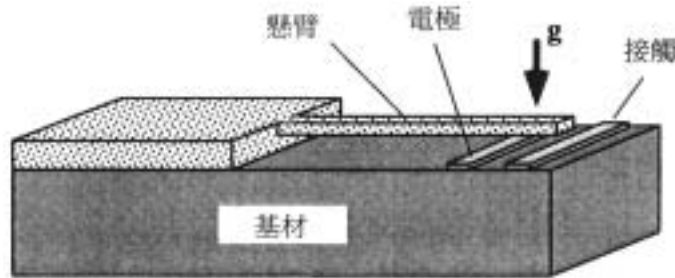


圖 6.22 加速度量測器之設計。根據 [Fick 93]。



## Capacitive Cantilever Microsensor

- A sawtooth voltage is applied in defined steps across the cantilever and the electrode.
- Electrostatic force acting on the cantilever increases with the applied voltage until contact occurs.
- For a cantilever length of 120-500  $\mu\text{m}$ , the microsensor sensitivity is in a range of 0.6-100 mV/g.

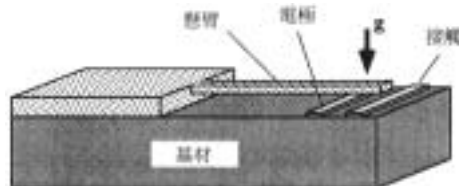


圖 6.22 加速度量測器之設計。根據 [Fick 93]。



## Capacitive Cantilever Microsensor

- Made of polysilicon by the dry etching process.
- Microstructure height (polysilicon) = 2.2  $\mu\text{m}$ .
- The gap attained between the cantilever and the contact strip is 1.5  $\mu\text{m}$ .

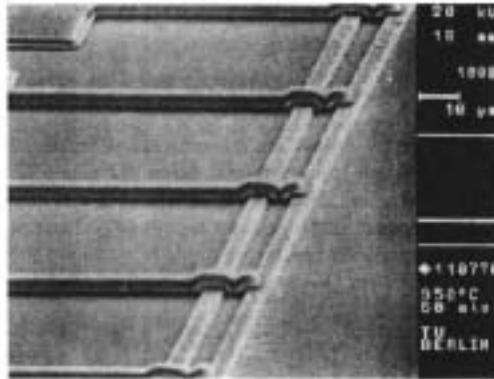


圖 6.23 感測器之微構造。感測器由柏林技術大學 (Department of Electrical Engineering, Microsensor and Microactuator Technology)。



## Piezoresistive Microsensor with Oil Damping

- Oil dampen the resonance of the suspended mass.
- The cantilever is 480 X 200 X 12 ( $\mu\text{m}$ ); the seismic mass weighs 2 (mg).
- Measurement range
  - ▶ 20 ~ 50 g.

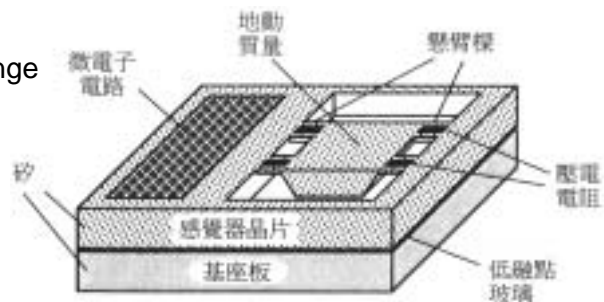


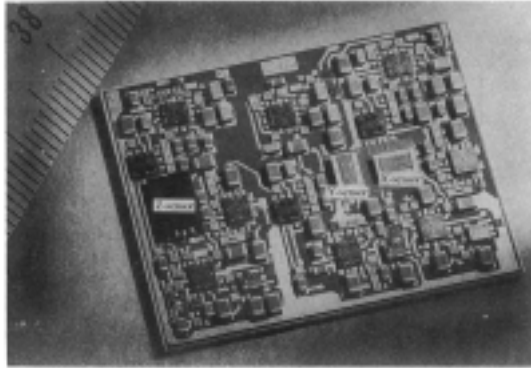
圖 6.24 微感測器之設計。根據 [Muro 92]。





## *Multi-sensor Acceleration Measurement System*

- 以SLIGA製作微機械電容感測器，整合三軸加速度計與放大電路、溫度補償於一晶片中



2 x 25 x 35 mm

Range:  $\pm 3$  g

Sensitivity 2.5 V/g

圖 6.35 三維度加速度量測系統 - 感測器 Karlsruhe Research Center, IMT  $\circ$

